SAW Filter 1582.4MHz (BW 46.61MHz) SMD 3.0x3.0 mm

MODEL NO.:TA2618A REV. NO.:1.0

A. MAXIMUM RATING:

RoHS Compliant

Lead-free soldering

1. Input Power Level: 15 dBm
2. DC Voltage : 3V
3. Operating Temperature: -40℃ to +105℃
4. Storage Temperature: -40℃ to +85℃
5. Moisture Sensitive Level (MSL): Level 1

Electrostatic **S**ensitive **D**evice (**ESD**)

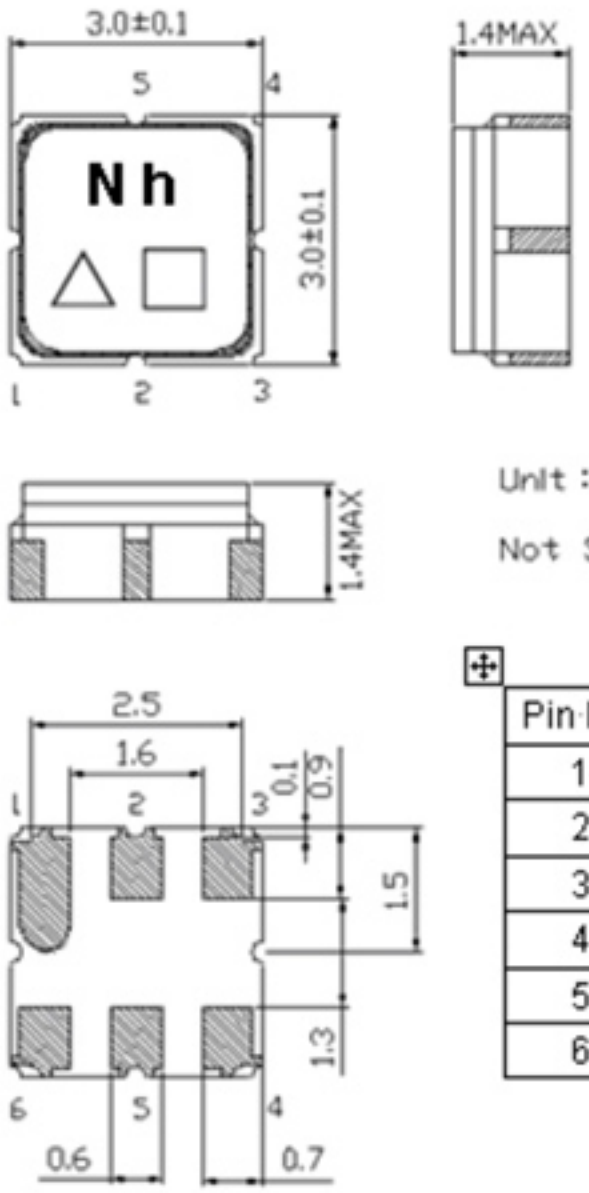
B. ELECTRICAL CHARACTERISTICS:

AEC-Q200

Item		Unit	Min.	Type.	-40℃ to +105℃
Center Frequency	**Fc**	MHz	-	1582.4	-
Insertion Loss	**IL**				
1)1574.42 ~ 1576.42 MHz		dB		1.2	2.0
2)1559.05 ~ 1563.15 MHz				1.7	2.2
3)1573.37 ~ 1577.47 MHz				1.3	2.0
4)1597.78 ~ 1605.66 MHz				1.5	4.0
GD Ripple (1597.55~1605.89 MHz)		dB	-	12	25
VSWR		-	-	-	-
1)1574.42 ~ 1576.42 MHz		-	-	1.6	2.0
2)1559.05 ~ 1563.15 MHz				1.3	2.0
3)1573.37 ~ 1577.47 MHz				1.7	2.0
4)1597.78 ~ 1605.66 MHz				1.4	2.0
Attenuation					
10 ~ 824 MHz		dB	30	38	-
824 ~ 925 MHz		dB	30	37	-
1427 ~ 1453 MHz		dB	40	47	-
1625 MHz		dB	25	42	-
1710 ~ 1785 MHz		dB	37	45	-
1850 ~ 1910 MHz		dB	38	47	-
1920 ~ 1980 MHz		dB	39	49	-
2400 ~ 2500 MHz		dB	35	45	-
2500 ~ 2570 MHz		dB	37	45	-

2600 ~ 3000 MHz	dB	20	41	-

C.OUTLINE DRAWING:



Pin No.	Symbol	Function
1	GND	Ground
2	IN	Input
3	GND	Ground
4	GND	Ground
5	OUT	Output
6	GND	Ground

Data code：See the table

WK	01	02	…	26	27	28	…	52
Code	A	B	…	Z	a	b	…	z

Δ Year code：See the table

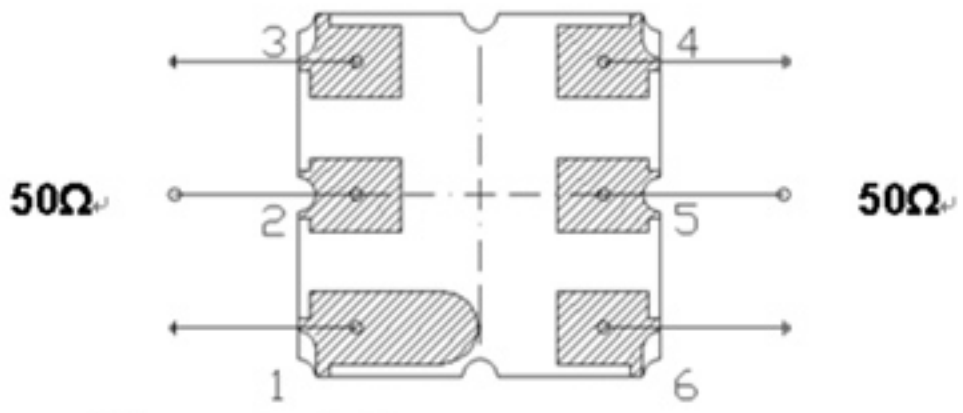
Year	2008	2009	2010	2011	…	2019	2020
Code	8	9	0	1	…	9	0

D. MEASUREMENT CIRCUIT:

(2): Unbalance Port

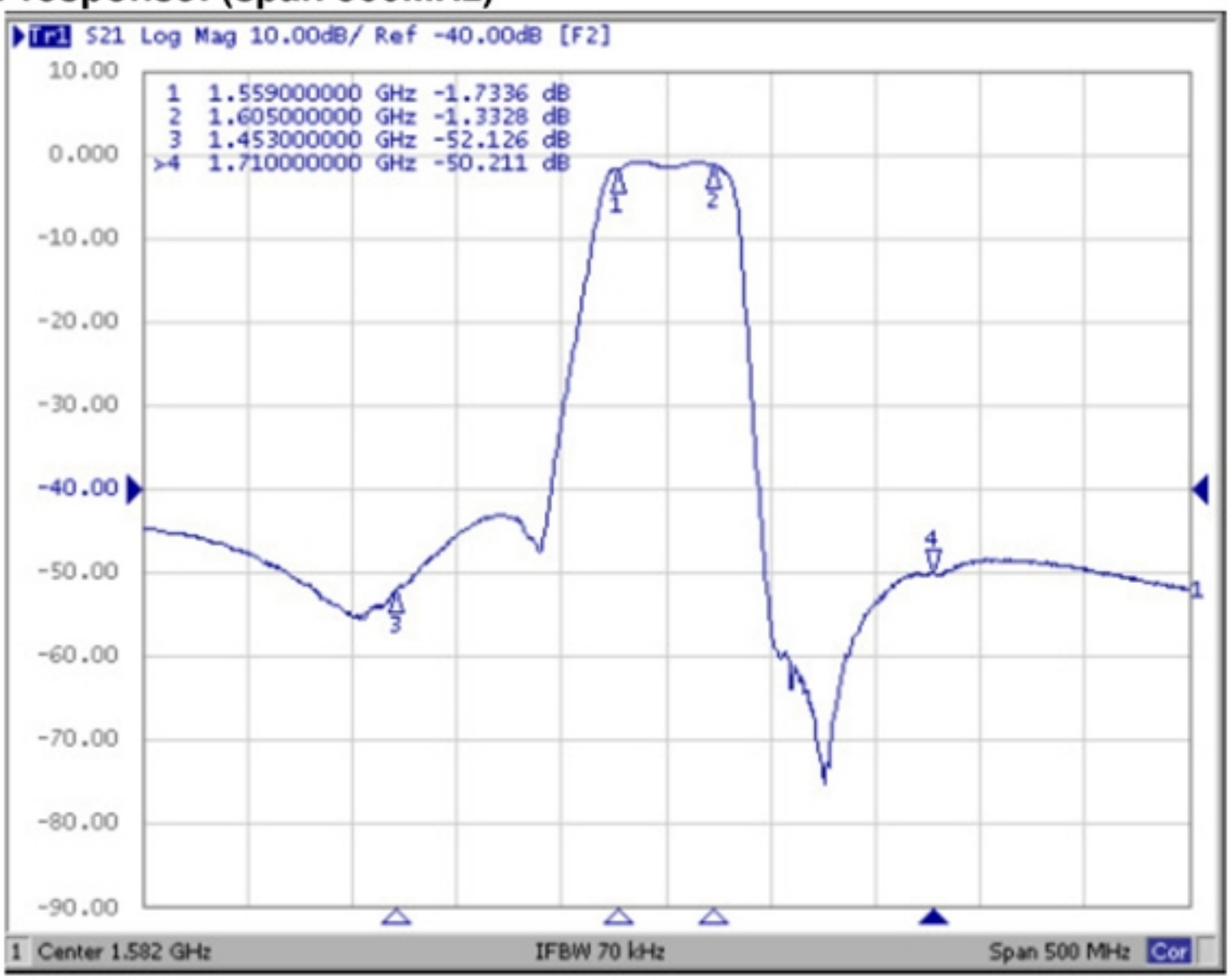
(5): Unbalance Port

Others: Ground

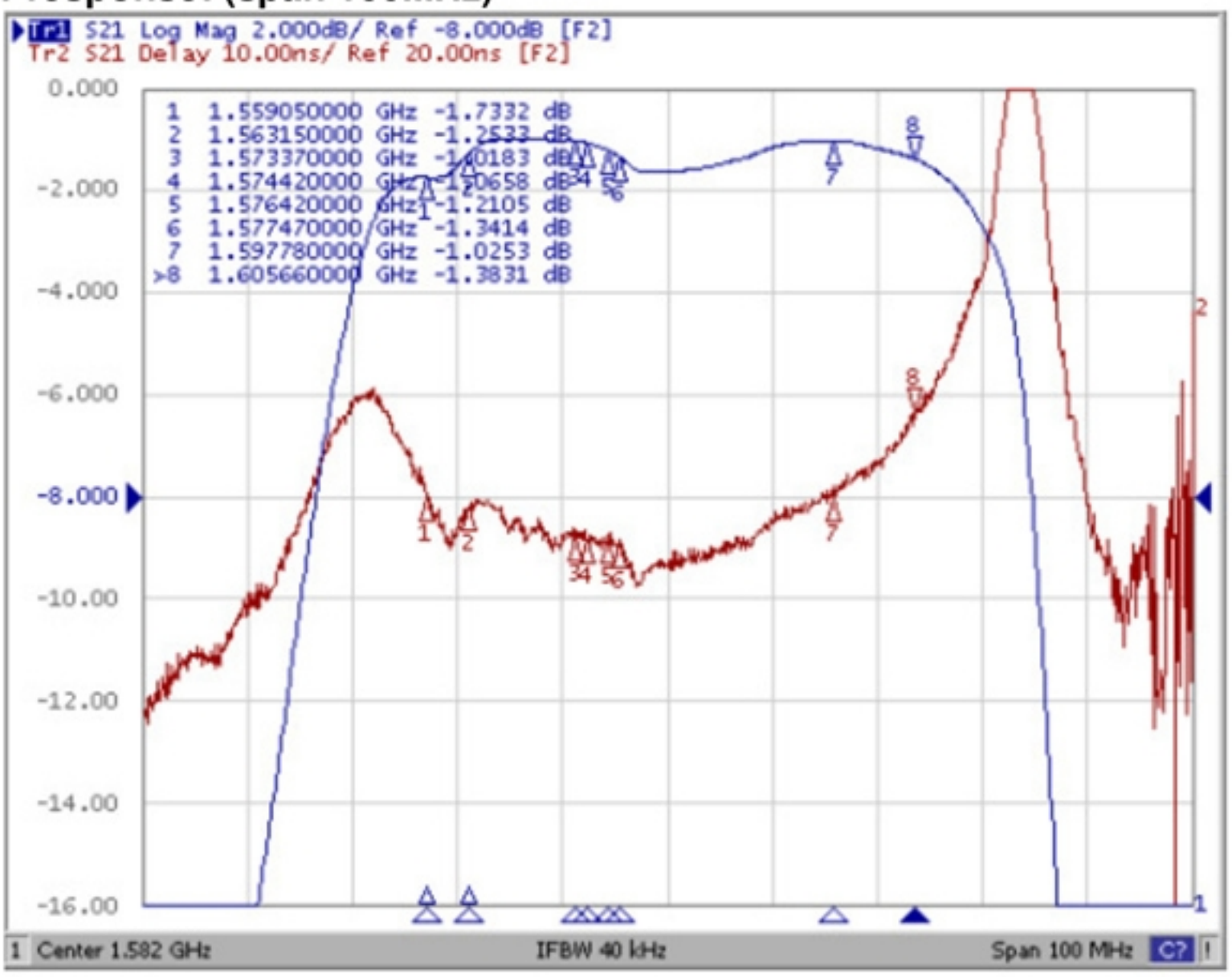


E. Frequency Characteristics:

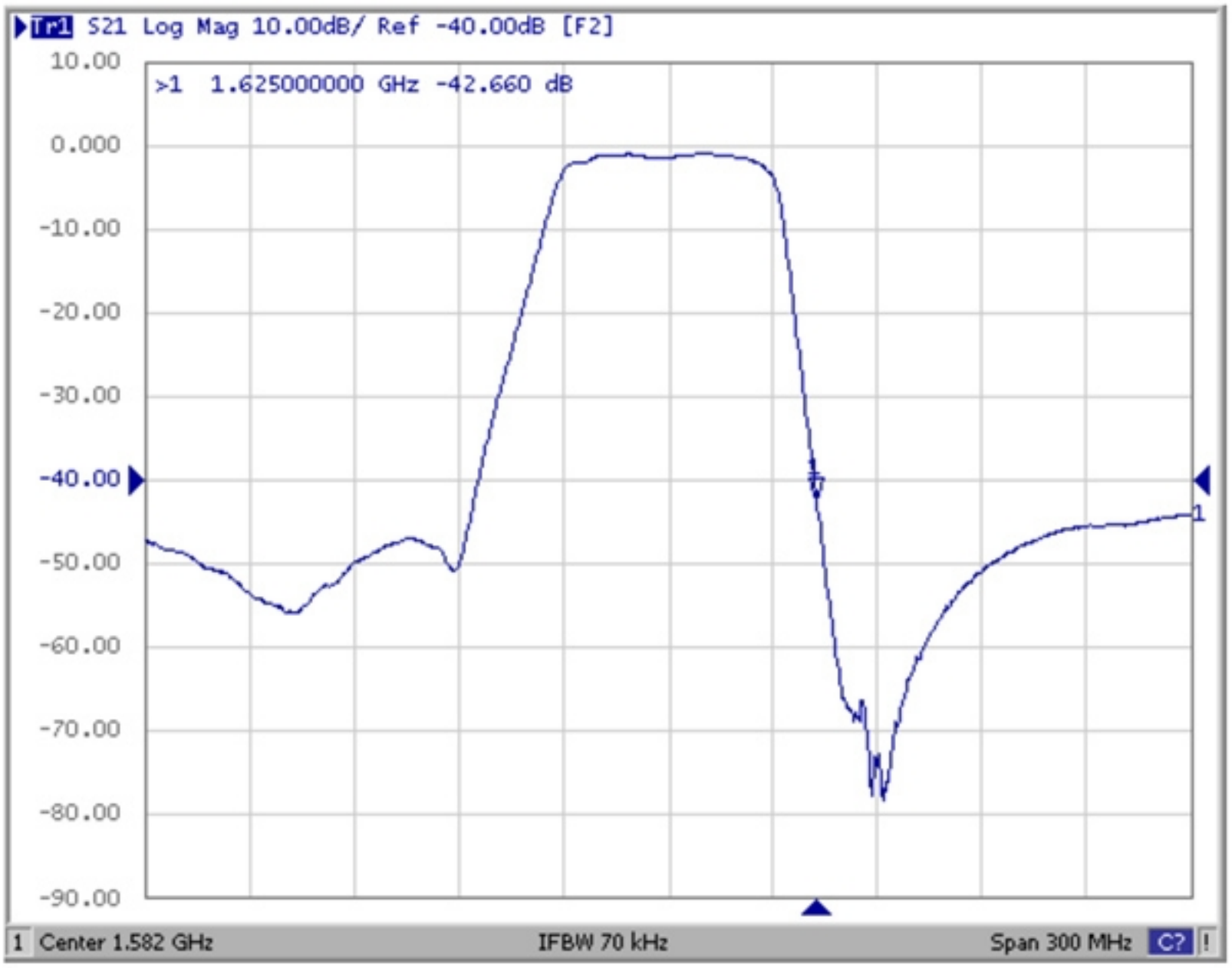
S21 response: (span 500MHz)



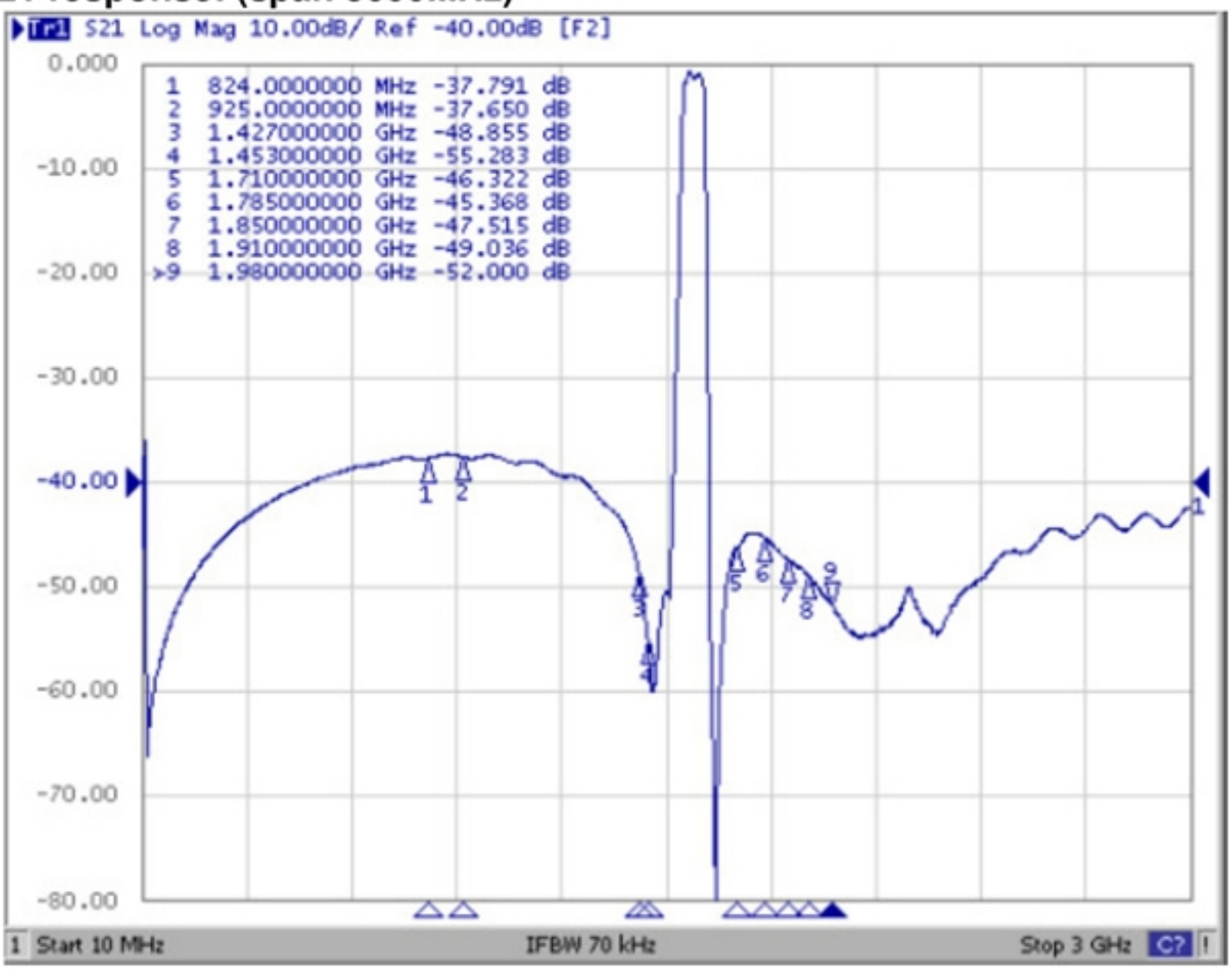
S21 response: (span 100MHz)



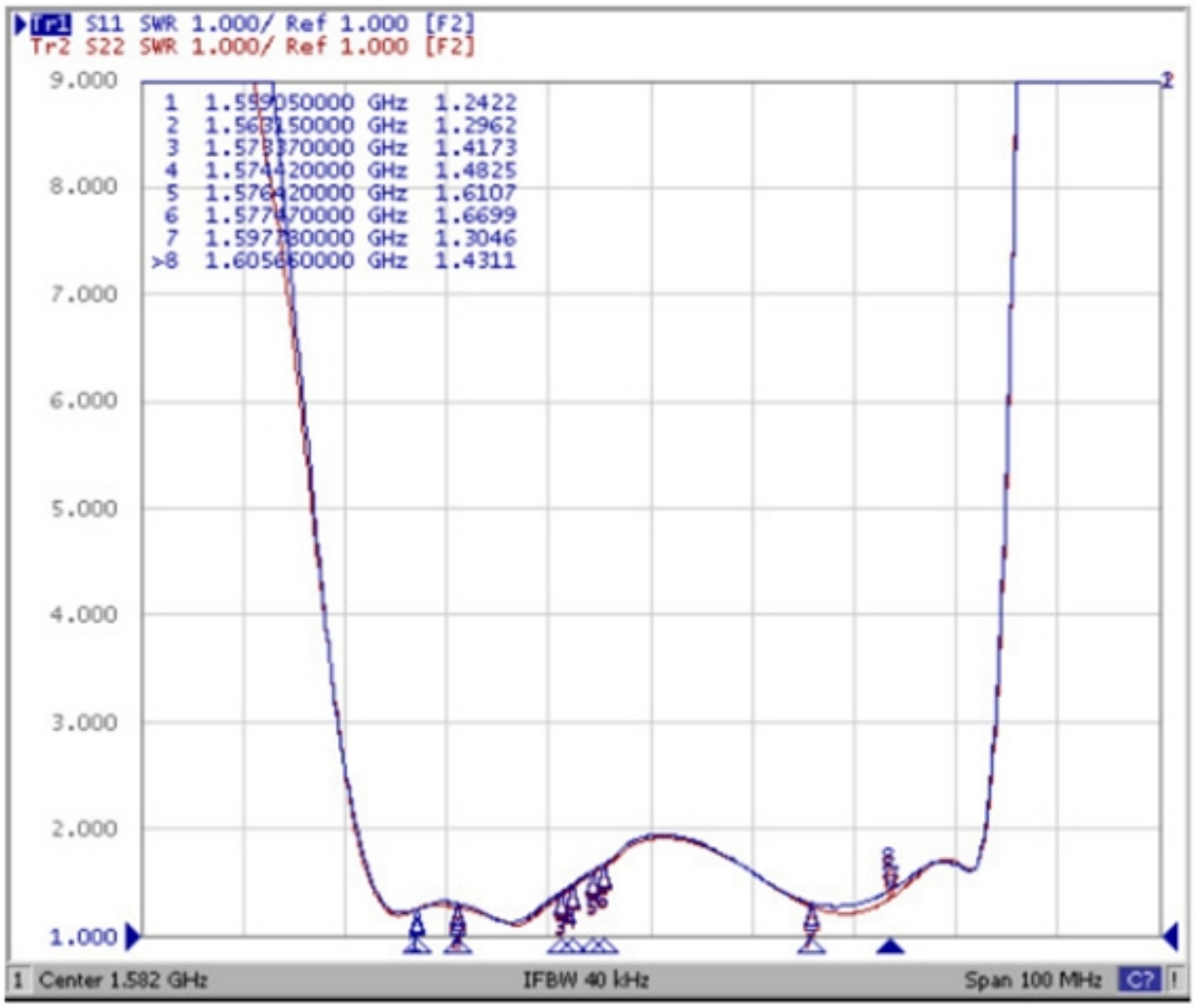
S21 response: (span 300MHz)



Sd21 response: (span 3000MHz)



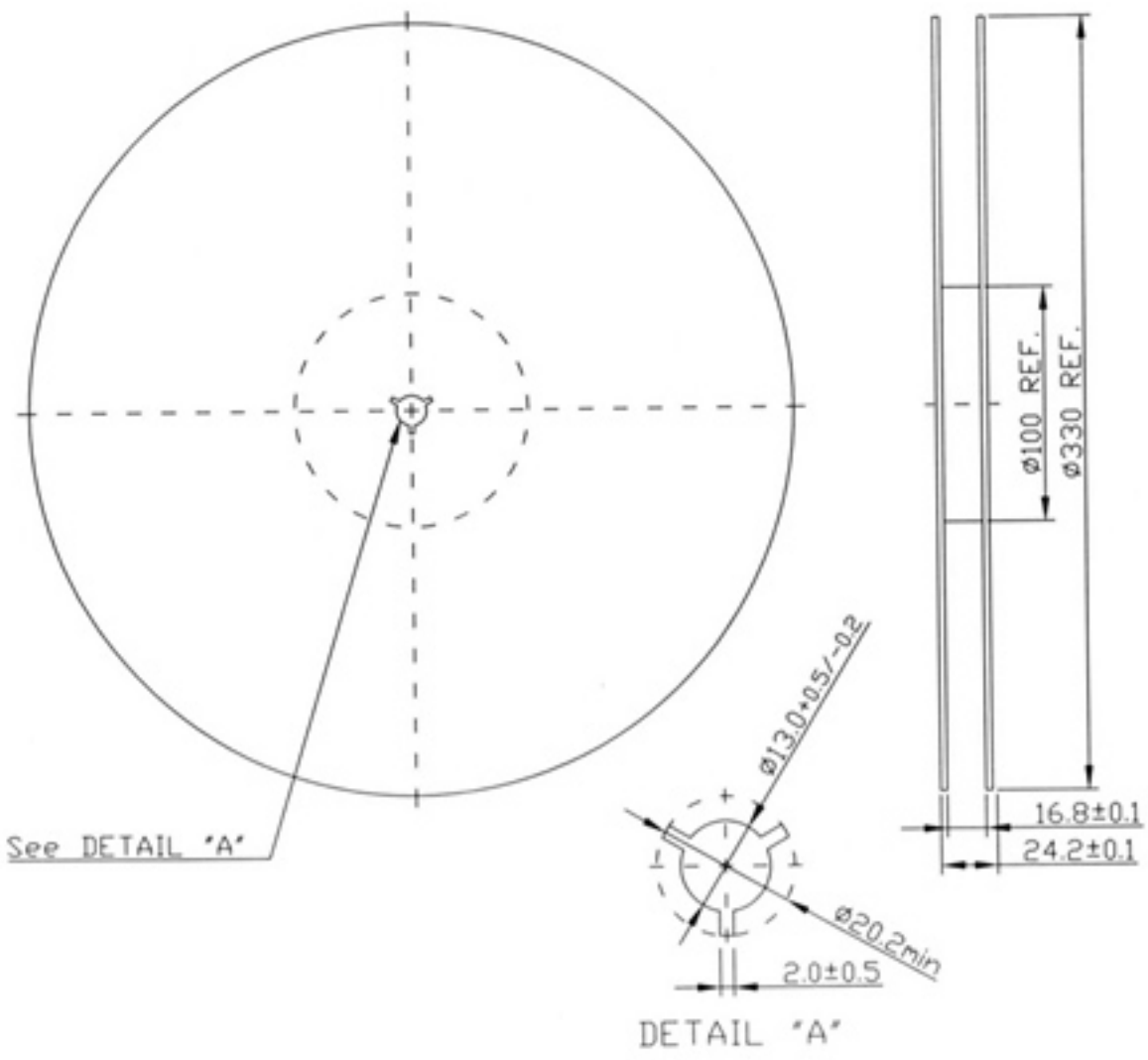
S11&S22 VSWR: (span 100MHz)



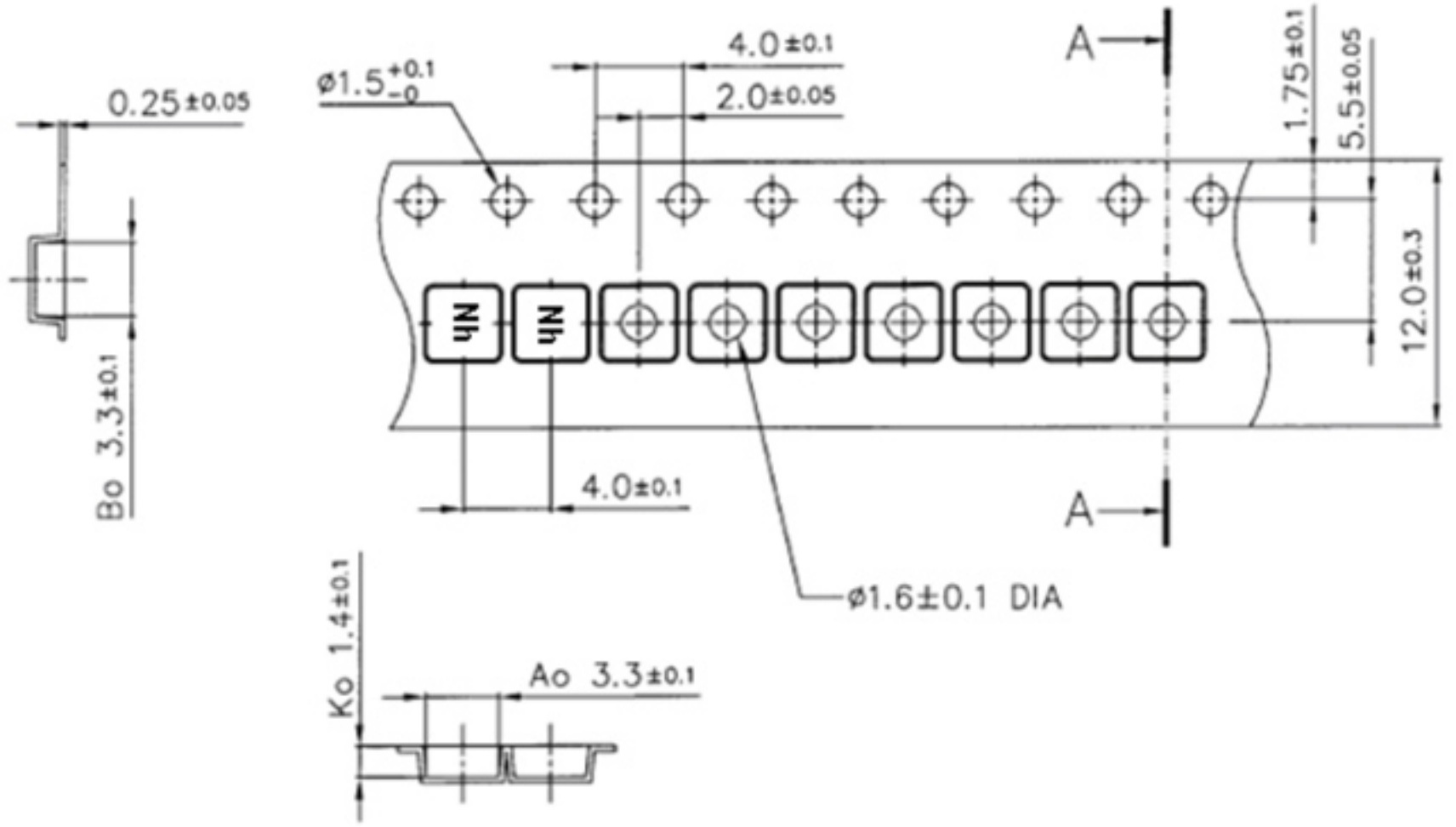
F. PACKING:

1. REEL DIMENSION

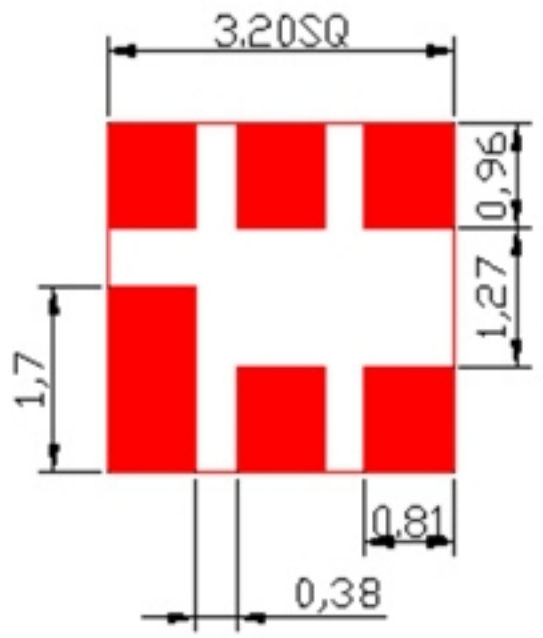
(Please refer to FR-75D10 for packing quantity)



2. TAPE DIMENSION



G. PCB Footprint:



H. STORAGE CONDITIONS:

1) Store in manufacturer's package or tightly reclosed box with the following conditions.

[Temperature: -10...+40℃, Humidity: 30...85%RH] Examine solderability before using this component, since more than 6 months storage might be a cause of degradation of solderability. Notice that long-term storage might be a cause of the discoloration.

2) To keep solderability of outer-electrode, do not store in the following environments.

- Ambient air containing corrosive gas (C12, H2S, NH3, SOX, NOX, etc.)
- Ambient air containing volatile or combustible gas
- In dusty place
- In the places where the water splashes and it tends to condense for high humid
- In direct sunlight
- In the places under the strong influence of static electricity or electric field strength

Contact the manufacturer before using the component in any of the above environments.

3) Do not open minimum packing unit until usage.

I. RECOMMENDED REFLOW PROFILE :

1. Preheating shall be fixed at 150~180℃ for 60~90 seconds.
2. Ascending time to preheating temperature 150℃ shall be 30 seconds min.
3. Heating shall be fixed at 220℃ for 50~80 seconds and at 260℃+0/-5℃ peak (20~40sec).
4. Time: 2 times.